

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ISC019N04NM5	**Issued**	24. February 2022
MA#	MA005708611		
Package	PG-TDSON-8-36	**Weight***	115.44 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.846	0.73	0.73	7332	7332
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		423	
	non noble metal	copper	7440-50-8	48.769	42.25	42.30	422474	423024
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	377	377
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		724	
	plastics	epoxy resin	-	6.600	5.72		57175	
	inorganic material	silicondioxide	60676-86-0	35.089	30.40	36.19	303966	361865
leadfinish	non noble metal	tin	7440-31-5	1.392	1.21	1.21	12055	12055
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1679	1679
solder	non noble metal	tin	7440-31-5	0.023	0.02		202	
	noble metal	silver	7440-22-4	0.029	0.03		253	
	non noble metal	lead	7439-92-1	1.116	0.97	1.02	9666	10121
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	17.131	14.84	14.85	148404	148598
clip plating	noble metal	silver	7440-22-4	1.059	0.92	0.92	9175	9175
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.57	2.57	25740	25774
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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